

Three Phase Rectifier Bridge

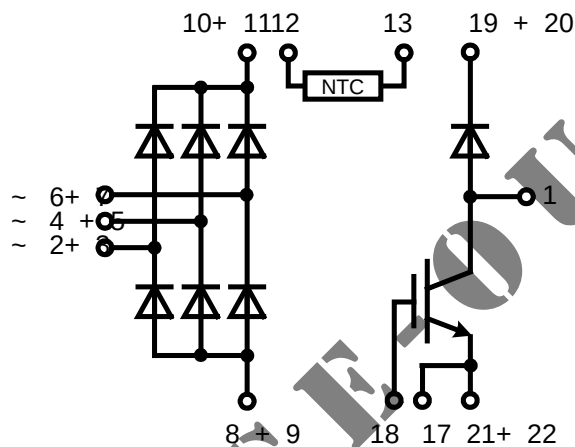
with IGBT and Fast Recovery Diode
for Braking System

Rectifier Diode	Fast Recov. Diode	IGBT
$V_{RRM} = 1600\text{ V}$	$V_{CES} = 1200\text{ V}$	$V_{ES} = 1200\text{ V}$
$I_{dAVM} = 116\text{ A}$	$V_F = 2.76\text{ V}$	$I_{B0} = 67\text{ A}$
$I_{FSM} = 700\text{ A}$	$I_{FSM} = 200\text{ A}$	$V_{CESat} = 3.5\text{ V}$

Preliminary data

Part name (marking on product)

VUB 116-16NO1



IXYS E72873

Features:

- Soldering connections for PCB mounting
- Convenient package outline
- Optional NTC

Application:

- Drive Inverters with braking system

Package:

- Two functions in one package
- Easy to mount with two screws
- Suitable for wave soldering
- High temperature and power cycling capability
- UL registered, E72873

Recommended replacement:
VUB 116-16NOXT

IGBT
Rat i n g s

S y m b o l	Def i n i t i o n s	C o n d i t i o n s	m i n .	t y p .	m a x .	U n i t
$V_{CE S}$	collector emitter voltage	$T_V = 25\text{ }^{\circ}\text{C}$ to $150\text{ }^{\circ}\text{C}$			1200	V
$V_{GE S}$	max. DC gate voltage	continuous	-20	+20		V
$V_{GE M}$	max. transient collector gate voltage	transient	-30	+30		V
$I_{C 25}$	collector current	$D C$ $T_C = 25\text{ }^{\circ}\text{C}$			95	A
$I_{C 80}$		$D C$ $T_C = 80\text{ }^{\circ}\text{C}$			67	A
P_{tot}	total power dissipation	$T_C = 25\text{ }^{\circ}\text{C}$			380	W
$V_{CE (sat)}$	collector emitter saturation voltage	$I_C = 100\text{ A}; V_{GE} = 15\text{ V}$ $v_{CE} = 25\text{ }^{\circ}\text{C}$			3.5	V
$V_{GE (th)}$	gate emitter threshold voltage	$I_C = 8\text{ mA}$ $v_{CE} = 25\text{ }^{\circ}\text{C}$	4.5		6.4	V
$I_{CE S}$	collector emitter leakage current	$V_{CE} = V_{CE S}; V_{GE} = 0\text{ V}$ $v_{CE} = 25\text{ }^{\circ}\text{C}$ $V_{CE} = 0.8\text{ V}; V_{GE} = 0\text{ V}$ $v_{CE} = 125\text{ }^{\circ}\text{C}$			0.1 0.5	mA mA
C_{ies}	input capacitance	$V_{CE} = 25\text{ V}; V_{GE} = 0\text{ V}; f = 1\text{ MHz}$			3.8	nF
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 720\text{ V}; I_C = 50\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 22\Omega; L = 100\text{ }\mu\text{H}$ $T_V = 125\text{ }^{\circ}\text{C}$	150			ns
$t_{d(off)}$	turn-off delay time		680			ns
E_{on}	turn-on energy per pulse		6			mJ
E_{off}	turn-off energy per pulse		4			mJ
$I_{C M}$	reverse bias safe operating area	$R_B SO_A = V_{CE} \pm 15\text{ V}; V_{GE} = R_G 22\Omega; L = 100\text{ }\mu\text{H}$ clamped inductive load $T_V = 125\text{ }^{\circ}\text{C}$			100	A
$V_{CE K}$	short circuit safe operating area	$V_{CE} = 720\text{ V}; V_{GE} = \pm 15\text{ V};$ $v_{CE} = T 125\text{ }^{\circ}\text{C}$ $R_G = 22\Omega$; non-repetitive			10	μs
(S C S OA)						
RBS OA	reverse bias safe operating area	$V_{CE} = 1200\text{ V}; V_{GE} = \pm 15\text{ V};$ $v_{CE} = T 125\text{ }^{\circ}\text{C}$ $R_G = 22\Omega; L = 100\text{ }\mu\text{H}$; clamped inductive load			100	A
$R_{thJ C}$	thermal resistance junction to case				0.33	K / W
$R_{thC H}$	thermal resistance case to heatsink				0.33	K / W

Fast Recovery Diode
Rat i n g s

S y m b o l	Def i n i t i o n s	C o n d i t i o n s	m i n .	t y p .	m a x .	U n i t
V_{RRM}	max. repetitive reverse voltage	$T_V = 150\text{ }^{\circ}\text{C}$			1200	V
I_{FAV}	average forward current	rect.; $d = 0.5$ $T_C = 80\text{ }^{\circ}\text{C}$			27	A
$I_{FRM S}$	rms forward current	rect.; $d = 0.5$ $T_C = 80\text{ }^{\circ}\text{C}$			38	A
$I_{FS M}$	max. surge forward current	$t = 10\text{ ms}$ $T_V = 45\text{ }^{\circ}\text{C}$			200	A
P_{tot}	total power dissipation	$T_C = 25\text{ }^{\circ}\text{C}$			130	W
V_{F0}	threshold voltage	$T_V = 150\text{ }^{\circ}\text{C}$			1.3	V
r_F	slope resistance	for power loss calculation only			16	m Ω
V_F	forward voltage	$I_F = 30\text{ A}$ $v_{CE} = 25\text{ }^{\circ}\text{C}$			2.76	V
I_R	reverse current	$V_R = V_{RRM}$ $T_V = 25\text{ }^{\circ}\text{C}$ $T_V = 125\text{ }^{\circ}\text{C}$			0.25 1	mA mA
I_{RM}	reverse recovery current	$I_F = 50\text{ A}; V_R = 100\text{ V}; dI/dt = -100\text{ A}/\mu\text{s}$	5.5		11	A
t_{rr}	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI/dt = -200\text{ A}/\mu\text{s}$	40			ns
$R_{thJ C}$	thermal resistance junction to case				0.9	K / W
$R_{thC H}$	thermal resistance case to heatsink				0.1	K / W

$T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise stated

Rectifier Diode

S y m b o l C o n d i t i o n s		R a t i n g s		m i n . t y p . m a x .	
V_{RRM}	max. repetitive reverse voltage	$T_V = 25\text{ }^{\circ}\text{C}$		1600	V
I_R	reverse current	$V_R = V_{RRM}$ $T_V = 25\text{ }^{\circ}\text{C}$ $T_V = 150\text{ }^{\circ}\text{C}$		0.1 2	mA mA
V_F	forward voltage	$I_F = 80\text{ A}$ $T_V = 25\text{ }^{\circ}\text{C}$		1.4 3	V
$I_{D(AV)M}$	max. average DC output current	rectangular; $d \leq \frac{1}{3}$; b ridge	$T_J = 80\text{ }^{\circ}\text{C}$	116	A
V_{F0}	threshold voltage	for power loss calculation only	$T_V = 150\text{ }^{\circ}\text{C}$	0.8 5	V
r_F	slope resistance			7.1	m Ω
R_{thJC}	thermal resistance junction to case	per diode	$T_J = 25\text{ }^{\circ}\text{C}$	0.65	K / W
R_{thCH}	thermal resistance case to heatsink		$T_V = 25\text{ }^{\circ}\text{C}$	0.1	K / W
P_{tot}	total power dissipation		$T_V = 25\text{ }^{\circ}\text{C}$	190	W
I_{FSM}	max. forward surge current	$t = 10\text{ ms (50 Hz)}$ $V_R = 0\text{ V}$	$T_V = 145\text{ }^{\circ}\text{C}$ $T_V = 150\text{ }^{\circ}\text{C}$	700 610	A A
I^2t	value for fusing	$t = 10\text{ ms (50 Hz)}$ $V_R = 0\text{ V}$	$T_V = 145\text{ }^{\circ}\text{C}$ $T_V = 150\text{ }^{\circ}\text{C}$	2450 1860	A ² s A ² s

Temperature Sensor NTC

S y m b o l D e f i n i t i o n s		C o n d i t i o n s		R a t i n g s		m i n . t y p . m a x .	
R_{25}	resistance	$T_C = 25\text{ }^{\circ}\text{C}$	4	75	5.25	Ω	K
$B_{25/85}$				3375			

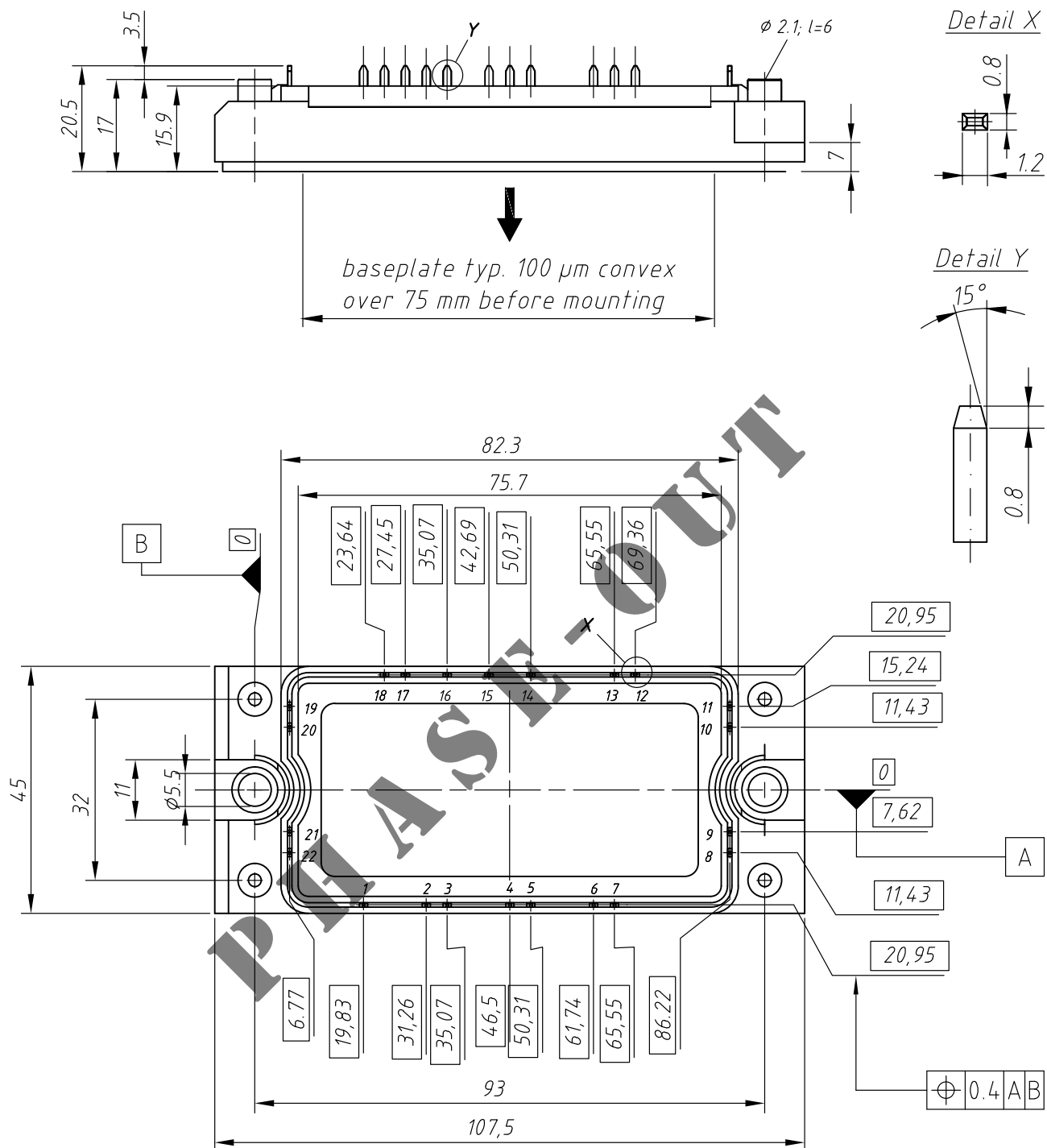
Module

S y m b o l D e f i n i t i o n s		C o n d i t i o n s		R a t i n g s		m i n . t y p . m a x .	
T_{VJ}	operating temperature		-40		125	$^{\circ}\text{C}$	
T_{VJM}	max. virtual junction temperature				150	$^{\circ}\text{C}$	
T_{stg}	storage temperature		-40		125	$^{\circ}\text{C}$	
V_{ISOL}	isolation voltage	$I_{ISO} \leq 1\text{ mA}; 50/60\text{ Hz};$ $t = 1\text{ min.}$ $t = 1\text{ s}$			2500 3000	V ~ V ~	
M_d	mounting torque	(M5)	2.7		3.3	N m	
d_s	creep distance on surface		12.7			mm	
d_A	strike distance through air		9.6			mm	
a	maximum allowable acceleration		50			m/s ²	
$R_{p\text{ in-chip}}$	thermal resistance pin to chip	$T_V = 25\text{ }^{\circ}\text{C}$			2	Ωm	
Weight					180	g	

 $T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise stated

Outline Drawing

D imensions in mm (1 mm = 0.03 9 4 ")



Product Mark in g

Orderin g	Part Nam e	M ark in g on	Produ ct Del iverin g M ode	Base Q ty	Orderin g C ode
Standard	V U B 116-16N O 1	V U B 116-16N O 1	B ox	6	4 9 68 5 5

IXYS reserves the right to change limits, test conditions and dimensions.

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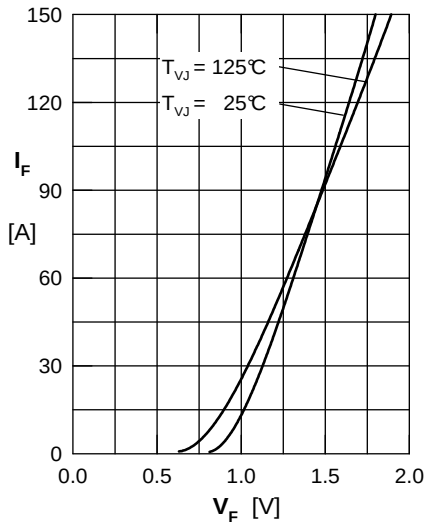


Fig. 1 Forward current vs. voltage drop per diode

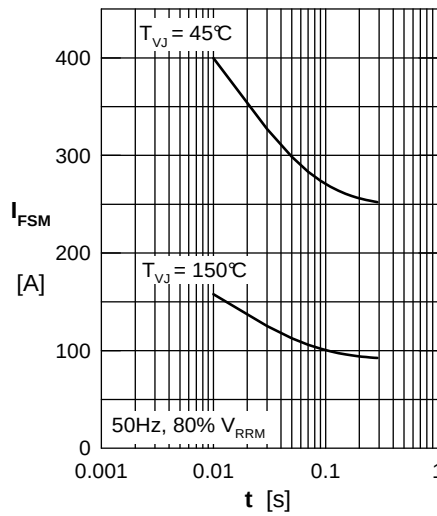


Fig. 2 Surge overload current

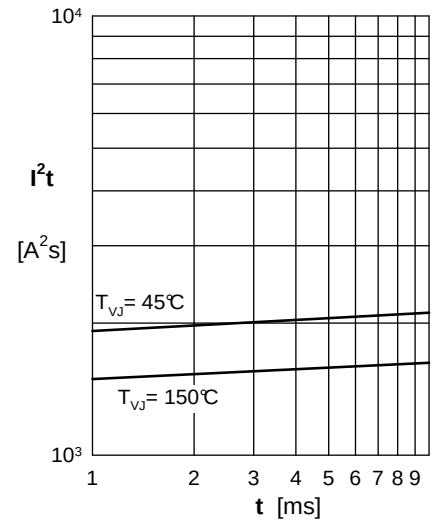


Fig. 3 I^2t versus time per diode

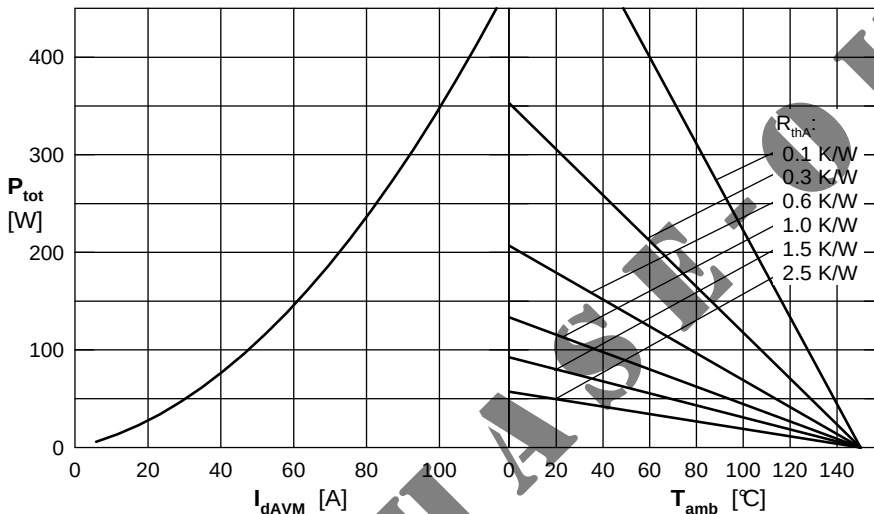


Fig. 4 Power dissipation versus direct output current and ambient temperature, sine 180°

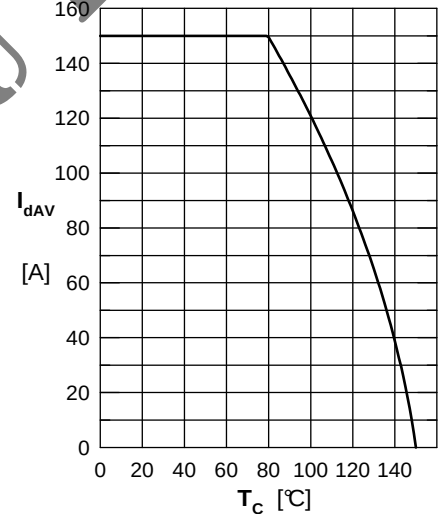


Fig. 5 Max. forward current vs. case temperature

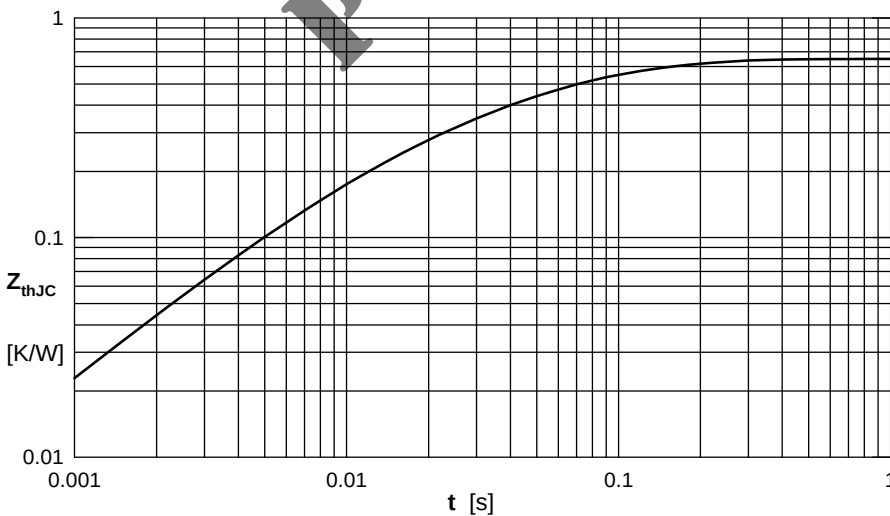


Fig. 6 Transient thermal impedance junction to case

R_i	τ_i
0.085	0.012
0.041	0.007
0.309	0.036
0.215	0.102

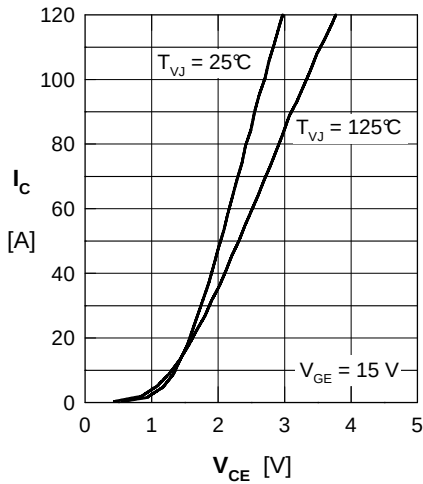


Fig. 7 Typ. output characteristics

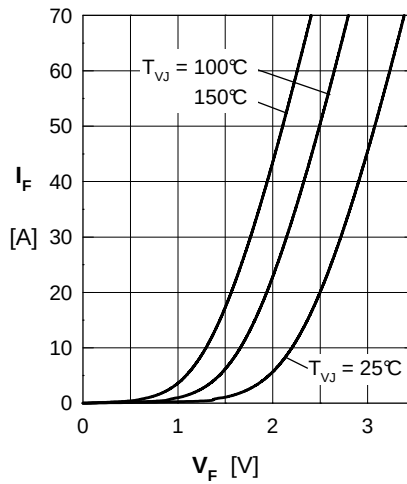


Fig. 8 Typ. forward characteristics of free wheeling diode

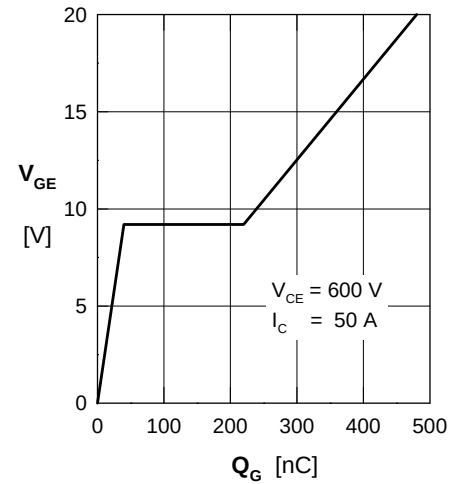


Fig. 9 Typ. turn on gate charge

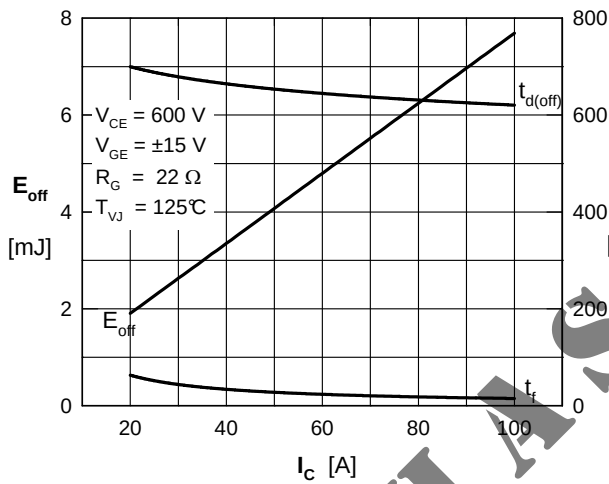


Fig. 10 Typ. turn off energy and switching times versus collector current

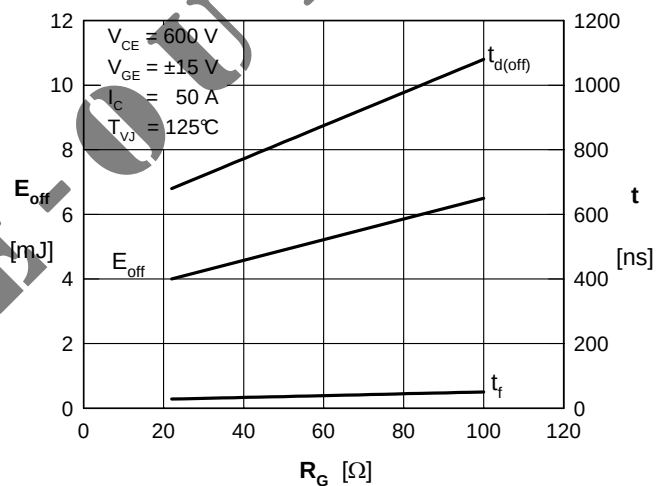


Fig. 11 Typ. turn off energy and switching times versus gate resistor

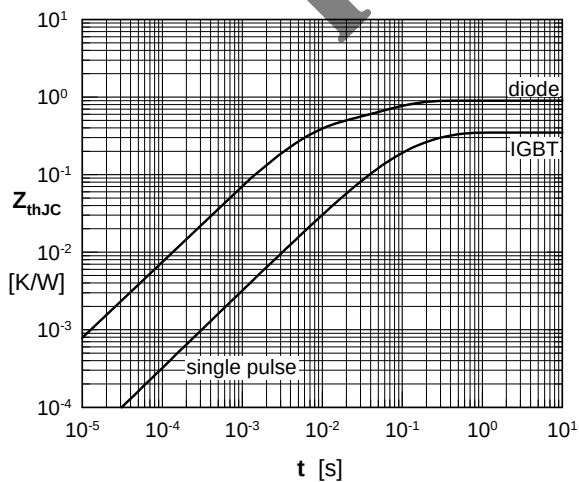


Fig. 12 Typ. transient thermal impedance

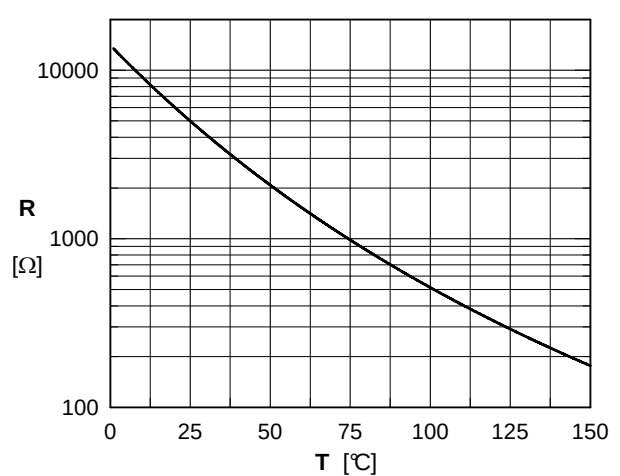


Fig. 13 Typ. thermistor resistance vs. temperature